Bondwire Material Change for Siliconix IC MLP5x5 microBUCK package

For further information, please contact your regional Vishay office.

CONTACT INFORMATION

Americas

Vishay Americas
2585 Junction Avenue
-
San Jose United States 95134- 1923
Phone: +1-408-988-8000
Fax:
-

Europe

Vishay Europe Sales GmbH
Dr Felix Zandman Platz 1
-
Selb Germany 95101
Phone: +49-9287-710
Fax:
business-europe@vishay.com

Asia

Vishay Intertechnlogy Asia Pte.Ltd
37A Tampines Street 92
#07-01
Singapore Singapore Singapore 528886
Phone: +65-6788-6668
Fax:
business-asia@vishay.com

Description of Change: Vishay has changed MLP5x5 microBUCK package bondwire from Au to Cu

Reason for Change: Copper bondwire conversion program

Expected Influence on Quality/Reliability/Performance: There will be no effect on performance, quality or reliability.

Part Numbers/Series/Families Affected: Please see materials list on the succeeding page.

Vishay Brand(S): Vishay Siliconix

Time Schedule:

Start Shipment Date: Saturday November 14, 2026

Sample Availability: Please contact your regional Vishay Sales office for sample availability.

Product Identification: Lot number

Qualification Data: Please see attached.

This PCN is considered approved, without further notification, unless we receive specific customer concerns before Saturday November 14, 2026 or as specified by contract.

Issued By: Lisette Saba, malinalisette.saba@vishay.com

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SIC448ED-T1-GE3	SIC461ED-T1-GE3	SIC462ED-T1-GE3	SIC463ED-T1-GE3	SIC464ED-T1-GE3
SIC466ED-T1-GE3	SIC467ED-T1-GE3	SIC468ED-T1-GE3	SIC469ED-T1-GE3	SIC471ED-T1-GE3
SIC472ED-T1-GE3	SIC473ED-T1-GE3	SIC474ED-T1-GE3	SIC476ED-T1-GE3	SIC477ED-T1-GE3
SIC478ED-T1-GE3	SIC479ED-T1-GE3			

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Qualification Data

September 2026

Reliability Test Results Summary

EVAL	STRESS	STEP	TEST CONDITION	HR/CYC /VOLT	S S	FAIL	DONE	TEST TYPE	FAIL CODE
2680262	BOND INT	0	BOND INT	0	40	0	X	VM	
		1	BOND INT	250	40	0	X	VM	
		2	BOND INT	500	40	0	X	VM	
	HAST	0	HAST	0	82	0	X	ET	
		1	HAST	100	82	0	X	ET	
	PRESSURE P	0	PRESSURE POT	0	82	0	X	ET	
		1	PRESSURE POT	96	82	0	X	ET	
	SOLDER DUN	0	SOLDER DUNK	168	55	0	X	ET	
		1	SOLDER DUNK	3	55	0	X	ET	
	SOLDERABIL	0	SOLDERABILITY	8	15	0	X	VM	
	TEMP CYCLE	0	T/C (H)	0	82	0	X	ET	
		1	T/C (H)	250	82	0	X	ET	
		2	T/C (H)	500	82	0	X	ET	
		3	T/C (H)	1000	82	0	X	ET	
	VP/SOLDER	0	PRODUCT PRECONDI	168G	246	0	X	ET	

PART NUMBER: AMSIC461ED-
LOT #: V38Y086.4
DATE CODE: T612AE
PURPOSE: MLP27-55/JAAFNRJANRFZ/SIC461

2680264	BOND INT	0	BOND INT	0	40	0	X	VM	
		1	BOND INT	250	40	0	X	VM	
		2	BOND INT	500	40	0	X	VM	
	PRESSURE P	0	PRESSURE POT	0	82	0	X	ET	
		1	PRESSURE POT	96	82	0	X	ET	
	SOLDER DUN	0	SOLDER DUNK	168	55	0	X	ET	
		1	SOLDER DUNK	3	55	0	X	ET	
	SOLDERABIL	0	SOLDERABILITY	8	15	0	X	VM	
	TEMP CYCLE	0	T/C (H)	0	82	0	X	ET	
		1	T/C (H)	250	82	0	X	ET	
		2	T/C (H)	500	82	0	X	ET	
		3	T/C (H)	1000	82	0	X	ET	
	VP/SOLDER	0	PRODUCT PRECONDI	168G	246	0	X	ET	

PART NUMBER: AMSIC467ED-
LOT #: V47Y048.2
DATE CODE: T612AD
PURPOSE: MLP27-55/JAAWNRFNNRFM/SIC467

2680470	HAST	0	HAST	0	82	0	X	ET	
		1	HAST	100	82	0	X	ET	
	VP/SOLDER	0	PRODUCT PRECONDI	168G	90	0	X	ET	

PART NUMBER: AMSIC467ED-
LOT #: V47Y048.2
DATE CODE: T612AD
PURPOSE: MLP27-55/JAAWNRFNNRFM/SIC467

EVAL	STRESS	STEP	TEST CONDITION	HR/CYC /VOLT	S S	FAIL	DONE	TEST TYPE	FAIL CODE
2680266	BOND INT	0	BOND INT	0	40	0	X	VM	
		1	BOND INT	250	40	0	X	VM	
		2	BOND INT	500	40	0	X	VM	
	HAST	0	HAST	0	82	0	X	ET	
		1	HAST	100	82	0	X	ET	
	PRESSURE P	0	PRESSURE POT	0	82	0	X	ET	
		1	PRESSURE POT	96	82	0	X	ET	
	SOLDER DUN	0	SOLDER DUNK	168	55	0	X	ET	
		1	SOLDER DUNK	3	55	0	X	ET	
	SOLDERABIL	0	SOLDERABILITY	8	15	0	X	VM	
	TEMP CYCLE	0	T/C (H)	0	82	0	X	ET	
		1	T/C (H)	250	82	0	X	ET	
		2	T/C (H)	500	81	0	X	ET	
		3	T/C (H)	1000	81	0	X	ET	
	VP/SOLDER	0	PRODUCT PRECONDI	168G	246	0	X	ET	

PART NUMBER: AMSIC468ED-
LOT #: V48Y041.4
DATE CODE: T612CD
PURPOSE: MLP27-55/JAAWNRFSNRFR/SIC468

EVAL	STRESS	STEP	TEST CONDITION	HR-CYC	S S	FAIL	DONE	TEST TYPE	FAIL CODE
2660072	DYN OP LIF	0	DYN OP LF (12	0	82	0	X	ET	
		1	DYN OP LF (12	168	82	0	X	ET	

PART NUMBER:SIC461ED-
DATE CODE: T612AE
PURPOSE: QUAKIFICATION

EVAL	STRESS	STEP	TEST CONDITION	HR-CYC	S S	FAIL	TEST DONE	TEST TYPE	FAIL CODE
2660073	DYN OP LIF	0	DYN OP LF (12	0	82	0	X	ET	
		1	DYN OP LF (12	168	82	0	X	ET	

PART NUMBER:SIC467ED-
DATE CODE: T612AD
PURPOSE: QUALIFICATION

EVAL	STRESS	STEP	TEST CONDITION	HR-CYC	S S	FAIL	TEST DONE	TEST TYPE	FAIL CODE
2660074	DYN OP LIF	0	DYN OP LF (12	0	82	0	X	ET	
		1	DYN OP LF (12	168	82	0	X	ET	

PART NUMBER:SIC468ED-
DATE CODE: T612CD
PURPOSE: QUALIFICATION